Datasheet

Current Sensor

# Current Sense Amplifier

## BD14210G-LA

### General Description

The BD14210G-LA current sense amplifier.
This is the product guarantees long time support in Industrial market.
This device operates from a single 2.7 V to 5.5 V power supply.
It has wide common mode voltage range from -0.2 V to +26 V, outputs analog voltage. The gain is 20 V/V.
The matched gain resistor minimizes gain error and realizes low offset voltage.
The input bias current is 1 µA (Typ) at typical condition. There is no need to adjust the gain error.

### Features

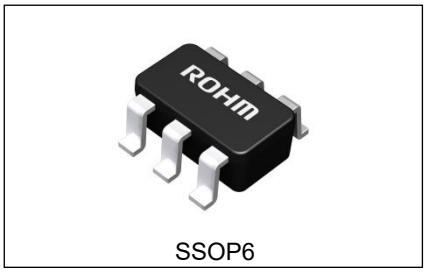
- Long Time Support Product for Industrial Applications.
- Wide Common Mode Voltage Range
- High Accuracy
- Low Offset Voltage
- Low Input Bias Current

### Key Specifications

- VDD Voltage Range: 2.7 V to 5.5 V
- Quiescent Current: 170 µA (Typ)
- Common Mode Voltage Range: -0.2 V to +26 V
- Gain: 20 V/V (Typ)
- Gain Accuracy: ±1.0 % (Max)
- Operating Temperature Range: -40 °C to +125 °C

### Package

| Package | W (Typ) x D (Typ) x H (Max) |
|---|---|
| SSOP6 | 2.9 mm x 2.8 mm x 1.25 mm |

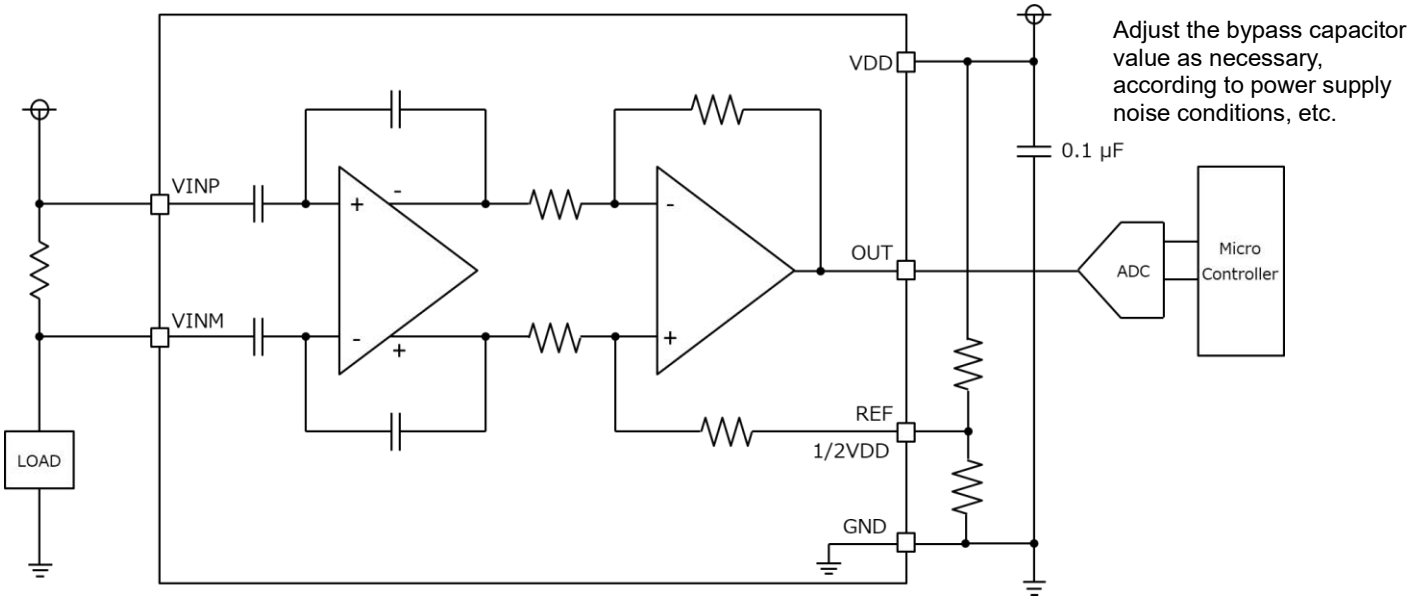



SSOP6

### Applications

- Industrial Equipment
- Telecom Equipment
- Over Current Detection

### Typical Application Circuit





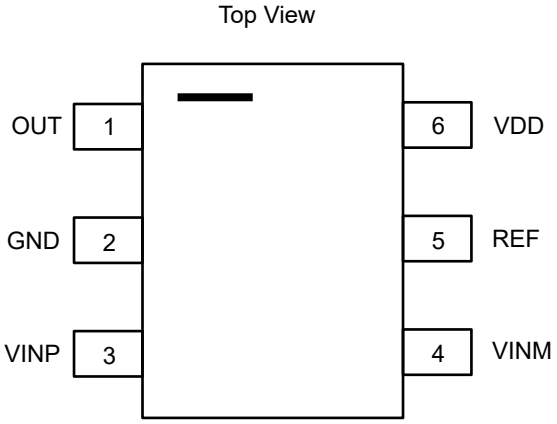
© 2022 ROHM Co., Ltd. All rights reserved.

# Contents

General Description....1
Features....1
Applications....1
Key Specifications....1
Package....1
Typical Application Circuit....1
Pin Descriptions....3
Pin Configurations....3
Absolute Maximum Ratings....4
Thermal Resistance....4
Recommended Operating Conditions....5
Electrical Characteristics....5
Typical Performance Curves....6
Figure 1. Quiescent Current vs Operating Temperature....6
Figure 2. Offset Voltage vs Operating Temperature....6
Figure 3. Gain Accuracy vs Operating Temperature....6
Figure 4. Input Bias Current vs Operating Temperature....6
Figure 5. H level Output Voltage vs Operating Temperature....7
Figure 6. L level Output Voltage vs Operating Temperature....7
Basic Explanation....8
Control Sequence....10
I/O Equivalence Circuits....11
Operational Notes....12
Ordering Information....14
Marking Diagram....14
Physical Dimension and Packing Information....15
Revision History....16


© 2022 ROHM Co., Ltd. All rights reserved.

## Pin Descriptions




## Pin Configurations

| Pin No. | Pin Name | Function |
|---|---|---|
| 1 | OUT | Current detection output |
| 2 | GND | Ground |
| 3 | VINP | Input of supply side of shunt resister |
| 4 | VINM | Input of load side of shunt resister |
| 5 | REF | Reference input |
| 6 | VDD | Power supply*(Note 1)* |

*(Note 1)* Dispose a bypass capacitor between VDD and GND.


© 2022 ROHM Co., Ltd. All rights reserved.

### Absolute Maximum Ratings (Ta = 25 °C)

| Parameter | Symbol | Rating | Unit |
|---|---|---|---|
| Power Supply Voltage | $V_{DD}$ | 7.0 | V |
| Common Mode Voltage | $V_{CM}$ | -0.2 to +26 | V |
| Input Voltage | $V_{IN}$ | -0.3 to $V_{DD}$+0.3 | V |
| Storage Temperature Range | Tstg | -55 to +150 | °C |
| Maximum Junction Temperature | Tjmax | 150 | °C |

***Caution 1:*** *Operating the IC over the absolute maximum ratings may damage the IC. The damage can either be a short circuit between pins or an open circuit between pins and the internal circuitry. Therefore, it is important to consider circuit protection measures, such as adding a fuse, in case the IC is operated over the absolute maximum ratings.*

***Caution 2:*** *Should by any chance the maximum junction temperature rating be exceeded the rise in temperature of the chip may result in deterioration of the properties of the chip. In case of exceeding this absolute maximum rating, design a PCB with thermal resistance taken into consideration by increasing board size and copper area so as not to exceed the maximum junction temperature rating.*

### Thermal Resistance *(Note 2)*

| Parameter | Symbol | Thermal Resistance (Typ) | | Unit |
|---|---|---|---|---|
| | | 1s*(Note 4)* | 2s2p*(Note 5)* | |
| SSOP6 | | | | |
| Junction to Ambient | $\theta_{JA}$ | 376.5 | 185.4 | °C/W |
| Junction to Top Characterization Parameter*(Note 3)* | $\Psi_{JT}$ | 40 | 30 | °C/W |

*(Note 2)* Based on JESD51-2A (Still-Air).
*(Note 3)* The thermal characterization parameter to report the difference between junction temperature and the temperature at the top center of the outside surface of the component package.
*(Note 4)* Using a PCB board based on JESD51-3.
*(Note 5)* Using a PCB board based on JESD51-7.

| Layer Number of Measurement Board | Material | Board Size |
|---|---|---|
| Single | FR-4 | 114.3 mm x 76.2 mm x 1.57 mmt |

| Top | |
|---|---|
| Copper Pattern | Thickness |
| Footprints and Traces | 70 µm |

| Layer Number of Measurement Board | Material | Board Size |
|---|---|---|
| 4 Layers | FR-4 | 114.3 mm x 76.2 mm x 1.6 mmt |

| Top | | 2 Internal Layers | | Bottom | |
|---|---|---|---|---|---|
| Copper Pattern | Thickness | Copper Pattern | Thickness | Copper Pattern | Thickness |
| Footprints and Traces | 70 µm | 74.2 mm x 74.2 mm | 35 µm | 74.2 mm x 74.2 mm | 70 µm |


© 2022 ROHM Co., Ltd. All rights reserved.

### Recommended Operating Conditions

| Parameter | Symbol | Min | Typ | Max | Unit | Condition |
|---|---|---|---|---|---|---|
| Power Supply Voltage | $V_{DD}$ | 2.7 | - | 5.5 | V | |
| Common Mode Voltage | $V_{CM}$ | -0.2 | - | +26 | V | VINP, VINM |
| Operating Temperature | Topr | -40 | +25 | +125 | °C | |

### Electrical Characteristics

**(Unless otherwise specified $V_{DD}$ = 5 V, $V_{REF}$ = 1/2 x $V_{DD}$, $V_{CM}$ = 12 V, $V_{SENSE}$ = ($V_{VINP}$ – $V_{VINM}$), Ta = 25 °C)**

| Parameter | Symbol | Min | Typ | Max | Unit | Condition |
|---|---|---|---|---|---|---|
| Power Supply | | | | | | |
| Quiescent Current | $I_{DD}$ | - | 170 | 280 | µA | $V_{SENSE}$ = 0 mV |
| Current Sense Amplifier | | | | | | |
| Offset Voltage | $V_{OS}$ | - | - | ±0.6 | mV | RTI*(Note 6)* , $V_{SENSE}$ = 0 mV |
| Gain | $G_{AIN}$ | - | 20 | - | V/V | |
| Gain Accuracy | $G_{ERR}$ | - | - | ±1.0 | % | $V_{OUT}$ = 0.5 V to $V_{DD}$-0.5 V<br>Ta = -40 °C to +125 °C |
| Nonlinearity Error | $L_{in}$ | - | ±0.01 | - | % | $V_{OUT}$ = 0.5 V to $V_{DD}$-0.5 V |
| Input Bias Current | $I_{VINM}$ | - | 1.0 | - | µA | $V_{SENSE}$ = 0 mV<br>Ta = -40 °C to +125 °C |
| High-level Output Voltage | $V_{OUT_H}$ | $V_{DD}$ – 0.02 | - | - | V | OUT, RL = 10 KΩ pulldown |
| Low-level Output Voltage | $V_{OUT_L}$ | - | - | GND + 0.05 | V | OUT, RL = 10 KΩ pullup |

*(Note 6)* RTI = Referred To Input


© 2022 ROHM Co., Ltd. All rights reserved.

### Typical Performance Curves

(Unless otherwise specified $V_{DD}$ = 5 V, $V_{REF}$ = 1/2 x $V_{DD}$, $V_{CM}$ = 12 V, $V_{SENSE}$ = ($V_{VINP}$ – $V_{VINM}$), Ta = 25 °C)

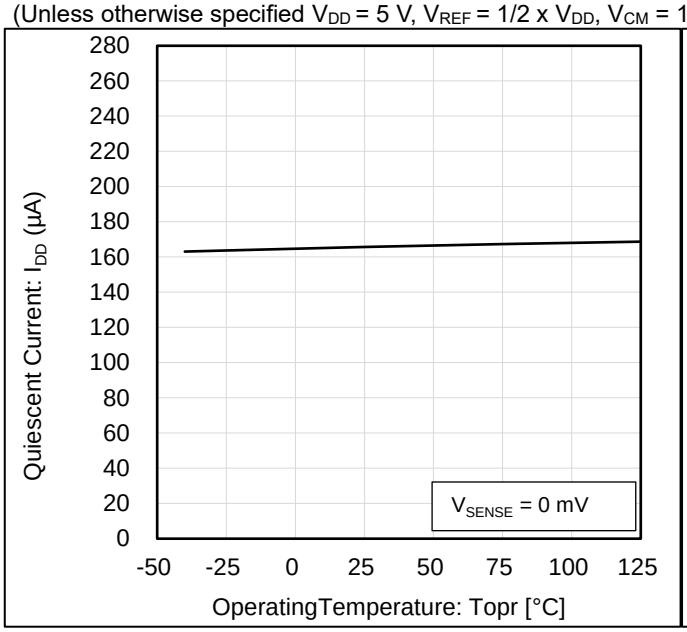



Figure 1. Quiescent Current vs Operating Temperature

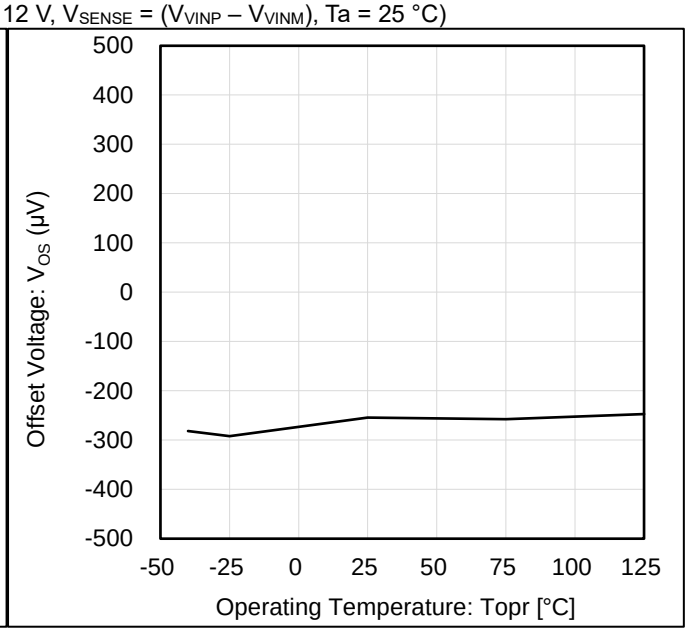



Figure 2. Offset Voltage vs Operating Temperature

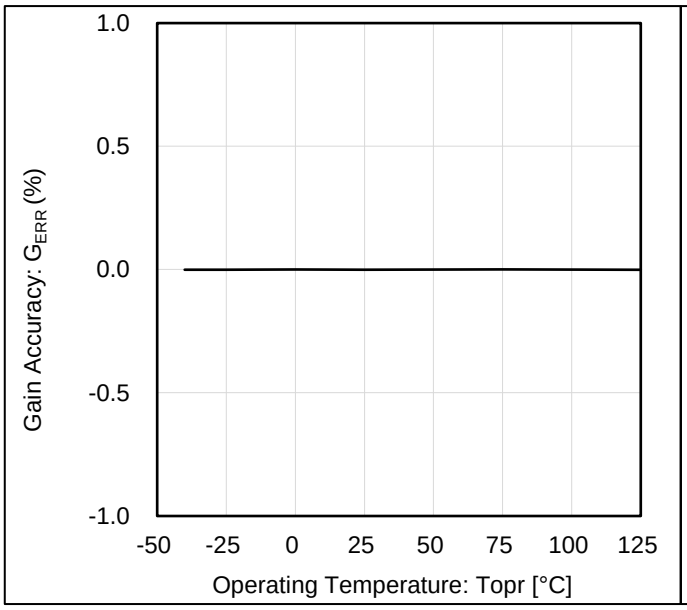



Figure 3. Gain Accuracy vs Operating Temperature

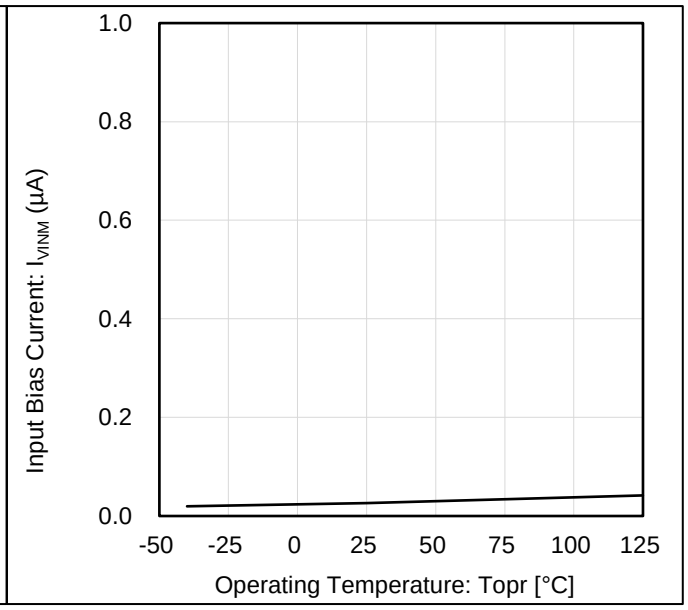



Figure 4. Input Bias Current vs Operating Temperature


© 2022 ROHM Co., Ltd. All rights reserved.

**Typical Performance Curves - continued**

(Unless otherwise specified $V_{DD}$ = 5 V, $V_{REF}$ = 1/2 x $V_{DD}$, $V_{CM}$ = 12 V, $V_{SENSE}$ = ($V_{VINP}$ – $V_{VINM}$), Ta = 25 °C)

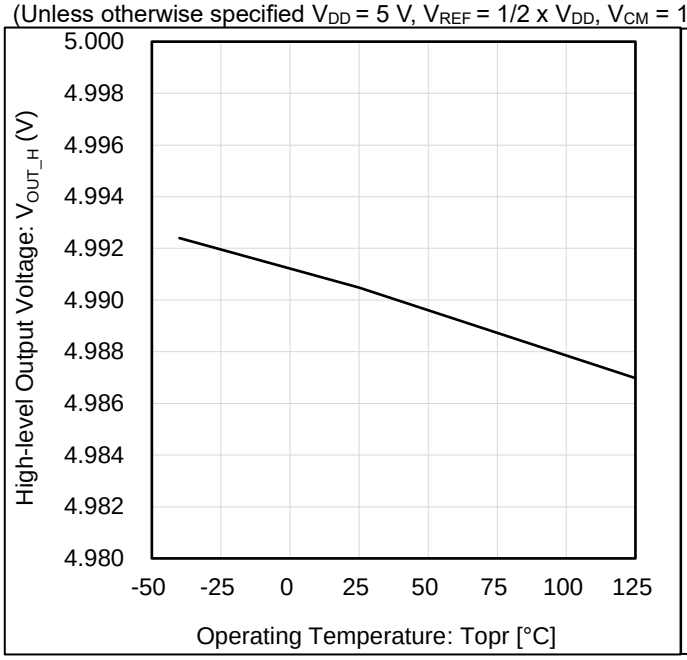



Figure 5. High-level Output Voltage vs Operating Temperature

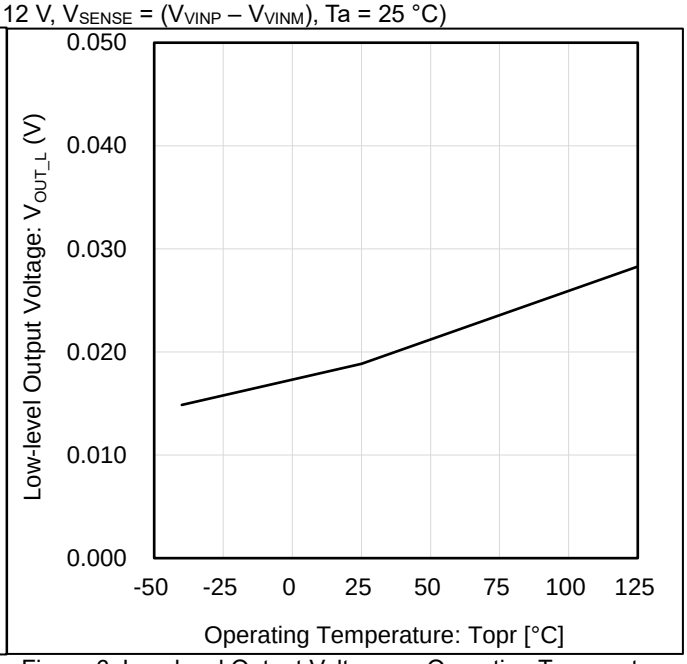



Figure 6. Low-level Output Voltage vs Operating Temperature


© 2022 ROHM Co., Ltd. All rights reserved.

### Basic Explanation

This IC has the structure specialized for Current Sense Amplifier and has the following features. Common mode voltage range is maximum 26 V with VDD of maximum 5.5 V, therefore it is possible to detect the current flowing in a power supply line exceeding VDD voltage. And its input bias current is very low.

This IC amplifies the voltage difference across the shunt resister between VINP and VINM and outputs a voltage with the REF pin as reference voltage.
If the current flows from VINP to VINM, OUT pin voltage is higher than REF pin voltage. If the current flows from VINM to VINP, OUT pin voltage is lower than REF pin voltage. When the voltages of VINP and VINM are equal, OUT pin voltage is equal to REF pin voltage.

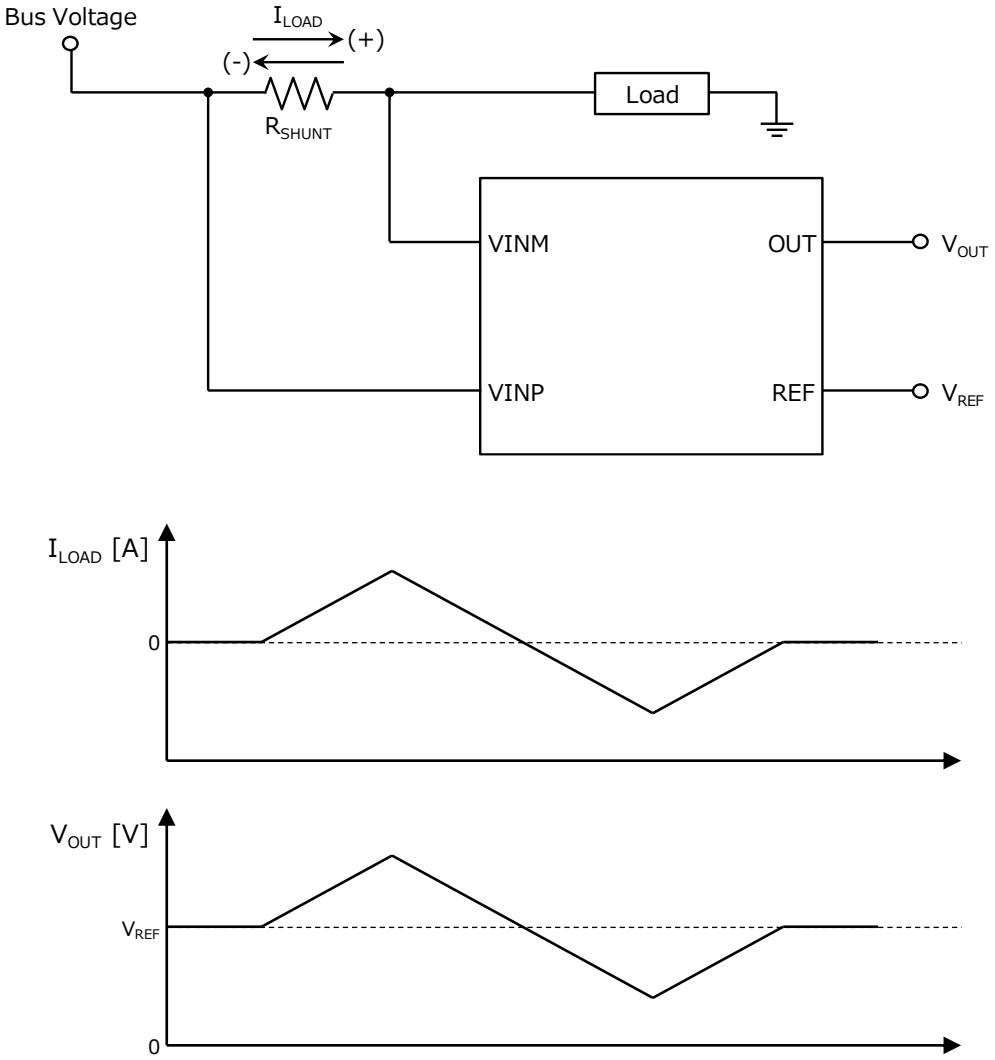



Figure 7. Basic Explanation

$V_{OUT}$ is calculated by the below formula.

$$V_{OUT} = (R_{SHUNT} \times I_{LOAD} \times GAIN) + V_{REF}$$

Where,
$R_{SHUNT}$ is the Shunt resistance
$I_{LOAD}$ is the Load current
*GAIN* is the Gain of Current Sense Amplifier
$V_{REF}$ is the REF pin voltage

Also, $V_{OUT}$ needs to be GND < $V_{OUT}$ < VDD.
$V_{OUT}$ is clipped to Low-level Output Voltage ($V_{OUT_L}$) when it's under GND.
$V_{OUT}$ is clipped to High-level Output Voltage ($V_{OUT_H}$) when it's over VDD.


© 2022 ROHM Co., Ltd. All rights reserved.

### Basic Explanation – continued

Input pin VINP and VINM needs to be connected to IC as close as possible in order to minimize the influence on series resistance of shunt resister.
For stability, dispose and connect a bypass capacitor for removing power source noise close to IC.

Selection of shunt resister
Shunt resister $R_{SHUNT}$ should be selected considering the accuracy of measuring current and the maximum power dissipation according to an application.
If the value of shunt resister is high, it minimizes the influence of offset and increases the accuracy of measuring current.
If the value of shunt resister is low, it reduces the power dissipation of VDD.
Shunt resister value is calculated by below formula.

$$R_{SHUNT} < (VDD - V_{REF}) / (abs(I_{LOADMAX}) \times GAIN)$$

Where
*VDD* is the Power Supply
$abs(I_{LOADMAX})$ is the Maximum of load current (absolute value)


© 2022 ROHM Co., Ltd. All rights reserved.

## Control Sequence

1. Control Sequence

1.1 Power supply start-up sequence

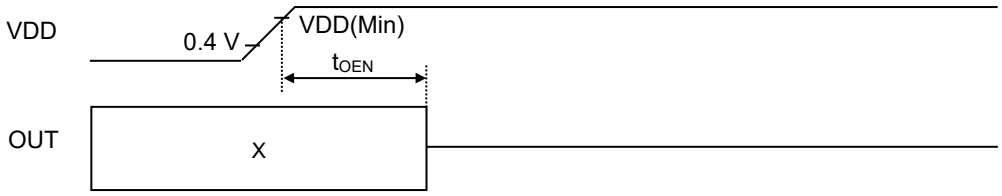



Figure 8. Timing Chart at Power ON

Stable time of OUT($t_{OEN}$) should be more than 1 ms.

1.2 Power supply end sequence

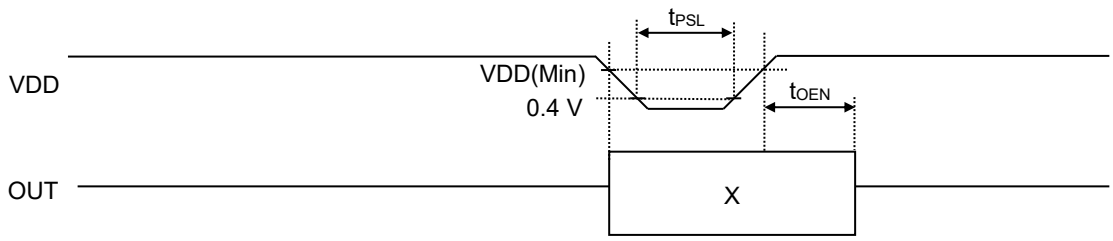
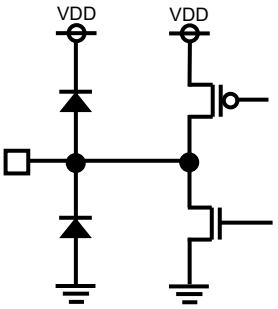
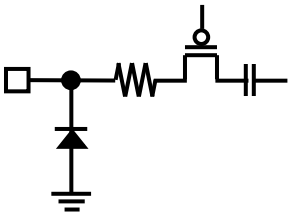
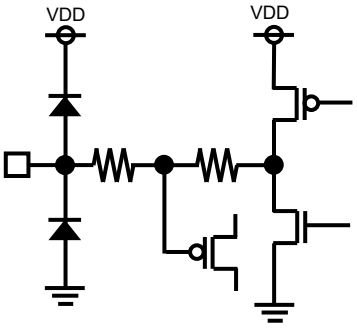



Figure 9. Timing Chart at Power OFF

Power off time($t_{PSL}$) should be more than 1 ms.
If VDD voltage is under the recommended operating condition, LSI is unstable state. In that case, set Power OFF and ON again. When the power is ON again, the period of VDD<0.4 V should be more than $t_{PSL}$.


© 2022 ROHM Co., Ltd. All rights reserved.

**I/O Equivalence Circuits**

| Pin Name | Equivalent Circuit Diagram | Pin Name | Equivalent Circuit Diagram |
|---|---|---|---|
| OUT |  | VINP<br>VINM |  |
| REF |  | | |


© 2022 ROHM Co., Ltd. All rights reserved.

## Operational Notes

1. **Reverse Connection of Power Supply**
   Connecting the power supply in reverse polarity can damage the IC. Take precautions against reverse polarity when connecting the power supply, such as mounting an external diode between the power supply and the IC's power supply pins.

2. **Power Supply Lines**
   Design the PCB layout pattern to provide low impedance supply lines. Furthermore, connect a capacitor to ground at all power supply pins. Consider the effect of temperature and aging on the capacitance value when using electrolytic capacitors.

3. **Ground Voltage**
   Ensure that no pins are at a voltage below that of the ground pin at any time, even during transient condition.

4. **Ground Wiring Pattern**
   When using both small-signal and large-current ground traces, the two ground traces should be routed separately but connected to a single ground at the reference point of the application board to avoid fluctuations in the small-signal ground caused by large currents. Also ensure that the ground traces of external components do not cause variations on the ground voltage. The ground lines must be as short and thick as possible to reduce line impedance.

5. **Recommended Operating Conditions**
   The function and operation of the IC are guaranteed within the range specified by the recommended operating conditions. The characteristic values are guaranteed only under the conditions of each item specified by the electrical characteristics.

6. **Inrush Current**
   When power is first supplied to the IC, it is possible that the internal logic may be unstable and inrush current may flow instantaneously due to the internal powering sequence and delays, especially if the IC has more than one power supply. Therefore, give special consideration to power coupling capacitance, power wiring, width of ground wiring, and routing of connections.

7. **Testing on Application Boards**
   When testing the IC on an application board, connecting a capacitor directly to a low-impedance output pin may subject the IC to stress. Always discharge capacitors completely after each process or step. The IC's power supply should always be turned off completely before connecting or removing it from the test setup during the inspection process. To prevent damage from static discharge, ground the IC during assembly and use similar precautions during transport and storage.

8. **Inter-pin Short and Mounting Errors**
   Ensure that the direction and position are correct when mounting the IC on the PCB. Incorrect mounting may result in damaging the IC. Avoid nearby pins being shorted to each other especially to ground, power supply and output pin. Inter-pin shorts could be due to many reasons such as metal particles, water droplets (in very humid environment) and unintentional solder bridge deposited in between pins during assembly to name a few.

9. **Unused Input Pins**
   Input pins of an IC are often connected to the gate of a MOS transistor. The gate has extremely high impedance and extremely low capacitance. If left unconnected, the electric field from the outside can easily charge it. The small charge acquired in this way is enough to produce a significant effect on the conduction through the transistor and cause unexpected operation of the IC. So unless otherwise specified, unused input pins should be connected to the power supply or ground line.


© 2022 ROHM Co., Ltd. All rights reserved.

## Operational Notes - continued

**10. Regarding the Input Pin of the IC**

This monolithic IC contains P+ isolation and P substrate layers between adjacent elements in order to keep them isolated. P-N junctions are formed at the intersection of the P layers with the N layers of other elements, creating a parasitic diode or transistor. For example (refer to figure below):

When GND > Pin A and GND > Pin B, the P-N junction operates as a parasitic diode.
When GND > Pin B, the P-N junction operates as a parasitic transistor.

Parasitic diodes inevitably occur in the structure of the IC. The operation of parasitic diodes can result in mutual interference among circuits, operational faults, or physical damage. Therefore, conditions that cause these diodes to operate, such as applying a voltage lower than the GND voltage to an input pin (and thus to the P substrate) should be avoided.

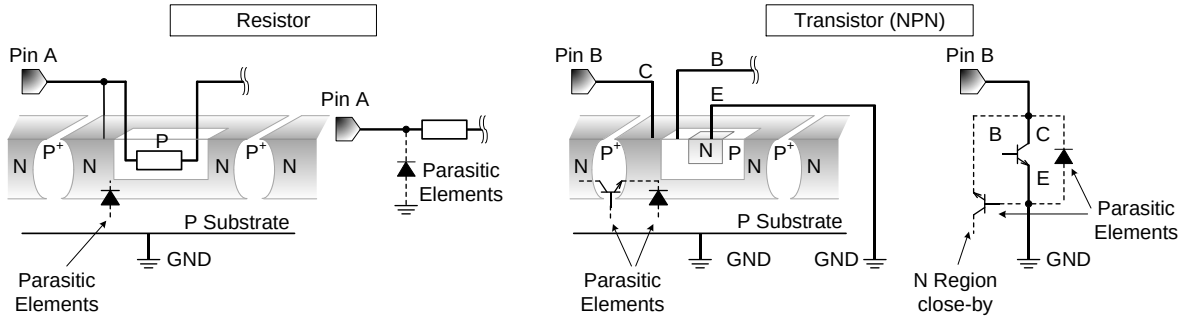


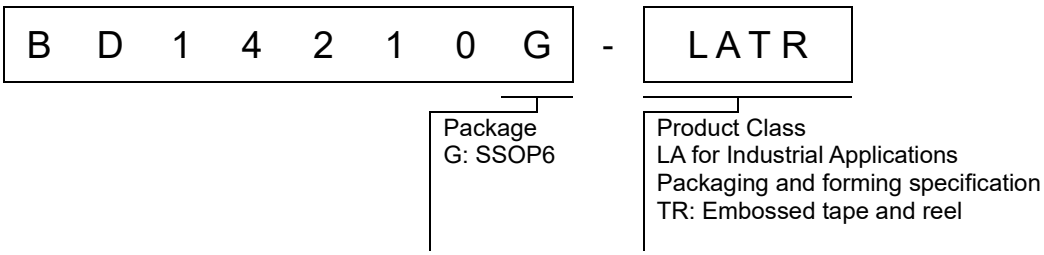

Figure 10. Example of Monolithic IC Structure

**11. Ceramic Capacitor**

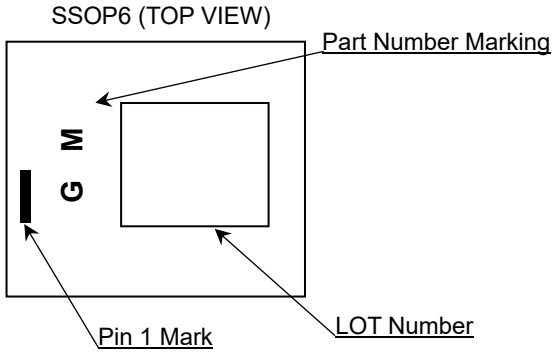
When using a ceramic capacitor, determine a capacitance value considering the change of capacitance with temperature and the decrease in nominal capacitance due to DC bias and others.


© 2022 ROHM Co., Ltd. All rights reserved.

### Ordering Information




### Marking Diagram

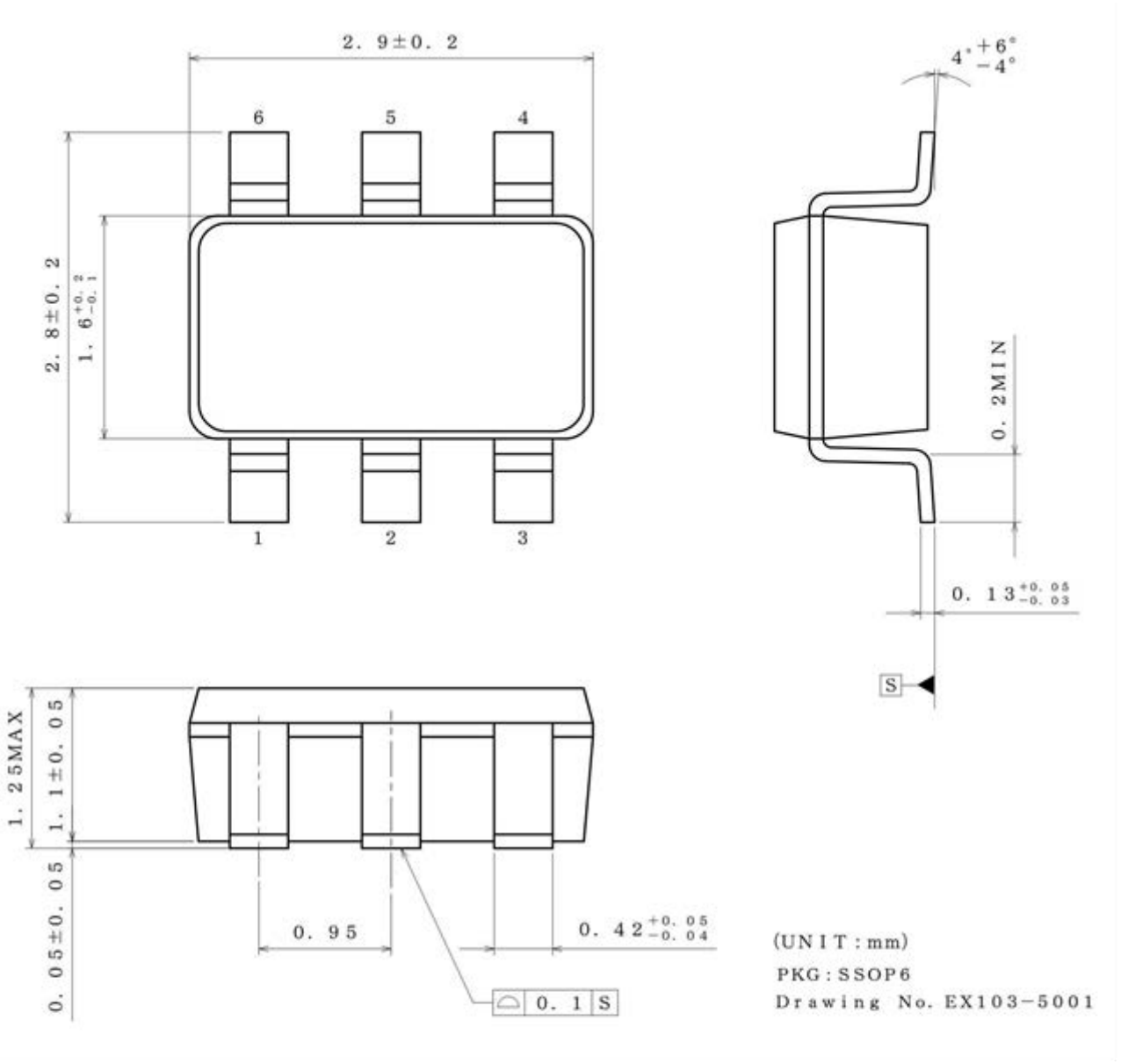




© 2022 ROHM Co., Ltd. All rights reserved.

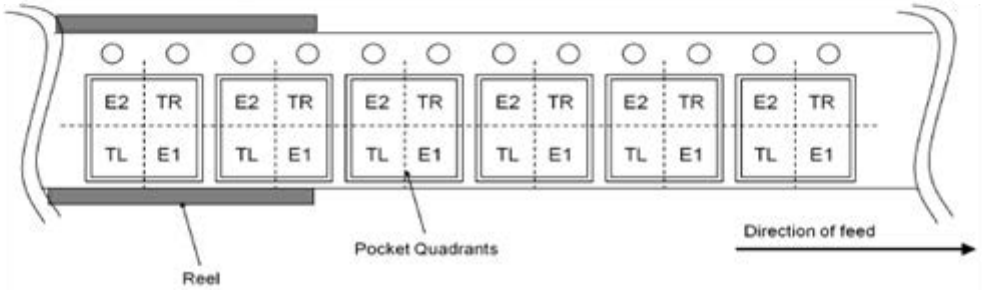
**Physical Dimension and Packing Information**

| Package Name | SSOP6 |
|---|---|




< Tape and Reel Information >

| Tape | Embossed carrier tape |
|---|---|
| Quantity | 3000pcs |
| Direction of feed | TR<br>( The direction is the 1pin of product is at the upper right when you hold reel on the left hand and you pull out the tape on the right hand ) |





© 2022 ROHM Co., Ltd. All rights reserved.

**Revision History**

| Date | Revision | Changes |
|---|---|---|
| 03.Mar.2022 | 001 | New Release |
| 28.Jun.2024 | 002 | Revision up only |


© 2022 ROHM Co., Ltd. All rights reserved.

# Notice

## Precaution on using ROHM Products

1. If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment (Note 1), aircraft/spacecraft, nuclear power controllers, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications

| JAPAN | USA | EU | CHINA |
|---|---|---|---|
| CLASSⅢ | CLASSⅢ | CLASSⅡb | CLASSⅢ |
| CLASSⅣ | | CLASSⅢ | |

2. ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
   [a] Installation of protection circuits or other protective devices to improve system safety
   [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure

3. Our Products are not designed under any special or extraordinary environments or conditions, as exemplified below. Accordingly, ROHM shall not be in any way responsible or liable for any damages, expenses or losses arising from the use of any ROHM's Products under any special or extraordinary environments or conditions. If you intend to use our Products under any special or extraordinary environments or conditions (as exemplified below), your independent verification and confirmation of product performance, reliability, etc, prior to use, must be necessary:
   [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
   [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
   [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including $Cl_2$, $H_2S$, $NH_3$, $SO_2$, and $NO_2$
   [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
   [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
   [f] Sealing or coating our Products with resin or other coating materials
   [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
   [h] Use of the Products in places subject to dew condensation

4. The Products are not subject to radiation-proof design.

5. Please verify and confirm characteristics of the final or mounted products in using the Products.

6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.

7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.

8. Confirm that operation temperature is within the specified range described in the product specification.

9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

## Precaution for Mounting / Circuit board design

1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.

2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification


© 2015 ROHM Co., Ltd. All rights reserved.

### Precautions Regarding Application Examples and External Circuits

1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.

2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

### Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of Ionizer, friction prevention and temperature / humidity control).

### Precaution for Storage / Transportation

1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
   [a] the Products are exposed to sea winds or corrosive gases, including $Cl_2$, $H_2S$, $NH_3$, $SO_2$, and $NO_2$
   [b] the temperature or humidity exceeds those recommended by ROHM
   [c] the Products are exposed to direct sunshine or condensation
   [d] the Products are exposed to high Electrostatic

2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.

3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.

4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

### Precaution for Product Label

A two-dimensional barcode printed on ROHM Products label is for ROHM's internal use only.

### Precaution for Disposition

When disposing Products please dispose them properly using an authorized industry waste company.

### Precaution for Foreign Exchange and Foreign Trade act

Since concerned goods might be fallen under listed items of export control prescribed by Foreign exchange and Foreign trade act, please consult with ROHM in case of export.

### Precaution Regarding Intellectual Property Rights

1. All information and data including but not limited to application example contained in this document is for reference only. ROHM does not warrant that foregoing information or data will not infringe any intellectual property rights or any other rights of any third party regarding such information or data.

2. ROHM shall not have any obligations where the claims, actions or demands arising from the combination of the Products with other articles such as components, circuits, systems or external equipment (including software).

3. No license, expressly or implied, is granted hereby under any intellectual property rights or other rights of ROHM or any third parties with respect to the Products or the information contained in this document. Provided, however, that ROHM will not assert its intellectual property rights or other rights against you or your customers to the extent necessary to manufacture or sell products containing the Products, subject to the terms and conditions herein.

### Other Precaution

1. This document may not be reprinted or reproduced, in whole or in part, without prior written consent of ROHM.

2. The Products may not be disassembled, converted, modified, reproduced or otherwise changed without prior written consent of ROHM.

3. In no event shall you use in any way whatsoever the Products and the related technical information contained in the Products or this document for any military purposes, including but not limited to, the development of mass-destruction weapons.

4. The proper names of companies or products described in this document are trademarks or registered trademarks of ROHM, its affiliated companies or third parties.


© 2015 ROHM Co., Ltd. All rights reserved.

**General Precaution**

1. Before you use our Products, you are requested to carefully read this document and fully understand its contents. ROHM shall not be in any way responsible or liable for failure, malfunction or accident arising from the use of any ROHM's Products against warning, caution or note contained in this document.

2. All information contained in this document is current as of the issuing date and subject to change without any prior notice. Before purchasing or using ROHM's Products, please confirm the latest information with a ROHM sales representative.

3. The information contained in this document is provided on an "as is" basis and ROHM does not warrant that all information contained in this document is accurate and/or error-free. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties resulting from inaccuracy or errors of or concerning such information.


© 2015 ROHM Co., Ltd. All rights reserved.